



Warpage control
High adhesion
Reduced solder flash

CV5386 CV5401

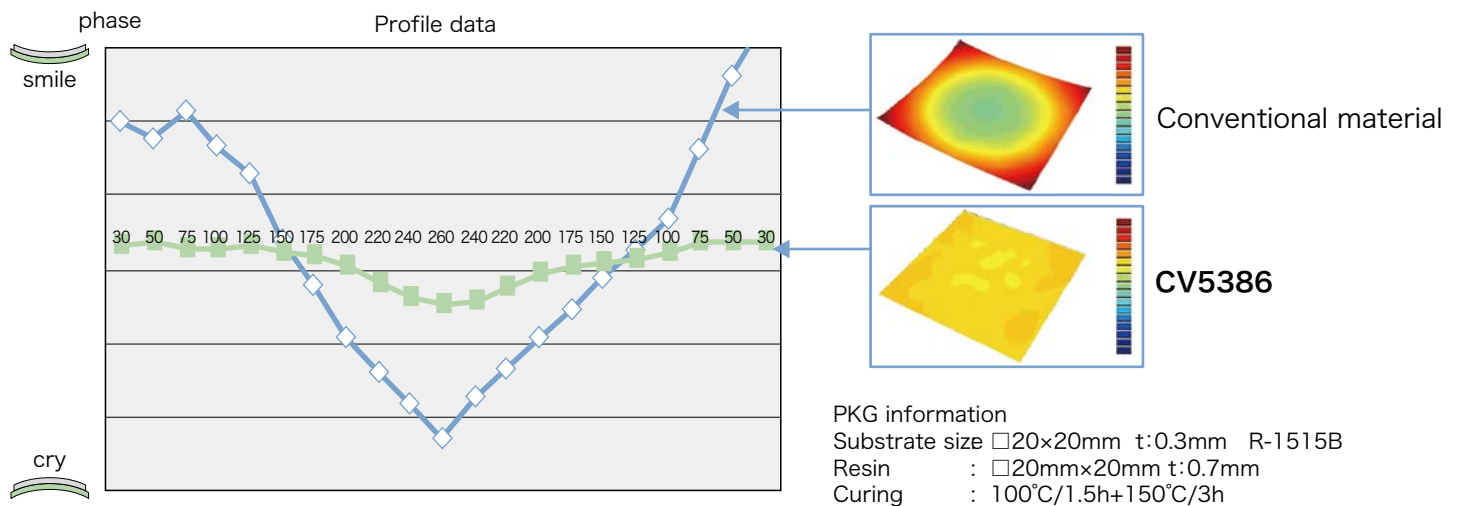
For SMD module
low warpage liquid encapsulant

Enhances process reliability by warpage control and high adhesion (Low warpage of ultrathin module is achieved). Solder flash during mounting reflow has been reduced, resulting in greatly decreasing the defect ratio. Large encapsulation area.

Applications IC Package/Mobile

Communication module (MAP, COB) for mobile devices such as notebook PC, digital camera, mobile phone, smartphone, tablet PC

Warpage behavior : Shadow moire analysis



Solder flash after mounting reflow has been reduced (X-ray observation)

